2SC3934

Silicon NPN epitaxial planar type

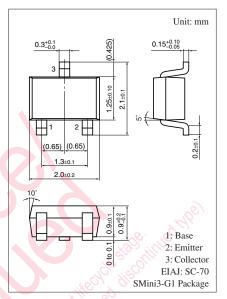
For high-frequency wide-band low-noise amplification

■ Features

- ullet High transition frequency f_T
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	15	V	
Collector-emitter voltage (Base open)	V _{CEO}	12	V	
Emitter-base voltage (Collector open)	V_{EBO}	2.5	V	
Collector current	I_C	30	mA	
Peak collector current	I_{CP}	50	mA	
Collector power dissipation	P _C	150	mW	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

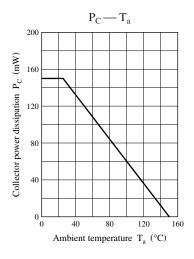


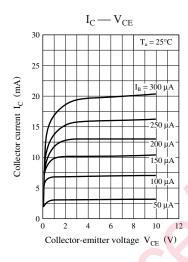
Marking Symbol: 1U

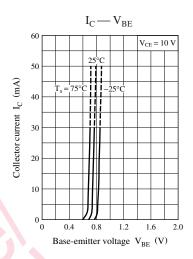
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

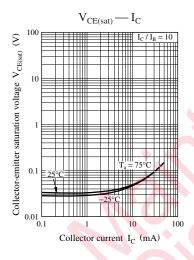
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 10 \text{ V}, I_{E} = 0$			100	nA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 2 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio	h_{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}$	40			
Transition frequency	f_{T}	$V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}, f = 0.8 \text{ GHz}$		4.5		GHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$			1.2	pF
(Common base, input open circuited)	Jelle 1					
Forward transfer gain	$ S_{21e} ^2$	$V_{CE} = 10 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$	9	12		dB
Maximum unilateral power gain	G_{UM}	$V_{CE} = 10 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$	12	14		dB
Noise figure	NF	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}, f = 0.8 \text{ GHz}$		1.3	2.5	dB

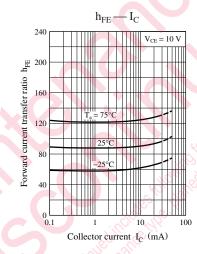
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

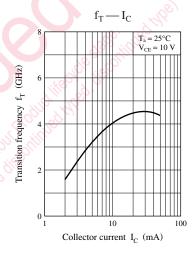


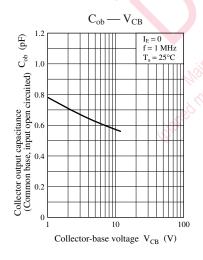


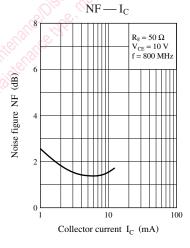


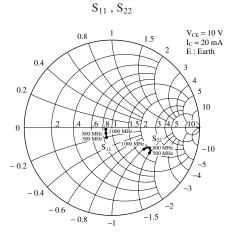


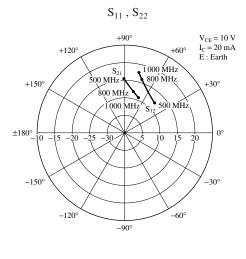












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